

PATENT

Docket No. MTI-31608

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Hock Chuan Tan, et al.
Serial No. : 10/068,159
Filing Date : February 5, 2002
For : Stacked Die in Die BGA Package
Group Art Unit : 2818
Confirmation No. : 8043
Examiner : Thao P. Le

CERTIFICATION OF SUBMISSION

I hereby certify that, on the date shown below, this correspondence is being transmitted via the Patent Electronic Filing System (EFS) addressed to Examiner LE at the U.S. Patent and Trademark Office.

Date: May 4, 2007 JM L. Palmatier

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

COMMUNICATION

Sir:

Examiners Le and Smith are thanked for the courtesies extended to the undersigned Attorney in their telephone conferences of May 2-3, 2007.

As discussed with Examiner Smith, enclosed herewith is an **Application Data Sheet**, which includes the information for the claim for foreign priority to Singapore application No. 200200134-5 (filed January 9, 2002) in the above-identified application.

The Examiner is requested to telephone the undersigned Attorney if further information or documentation is required.

Respectfully submitted,

Kristine M. Strodthoff

Dated: May 4, 2007

Kristine M. Strodthoff
Reg. No. 34,259

WHYTE HIRSCHBOECK DUDEK S.C.
555 East Wells Street, Suite 1900
Milwaukee, Wisconsin 53202-3819
(414) 273-2100
Customer No. 31870